

EXPRESSION OF INTEREST (EOI)

For Co-Development, Engineering, Manufacturing and Commercialization of a micron Resolution 3D Printer

Subject: Expression of Interest for the identification of Development cum Production industry (DcPP) partners for the joint submission of a project towards the Development of Advanced Photonics Packaging Technologies using Additive Manufacturing.

Department of Instrumentation and Applied Physics

Indian Institute of Science (IISc), Bengaluru

1. The objective of the Expression of Interests (EOI) –

The objective of this Expression of Interest (EOI) is to identify and empanel suitable Indian Industry Partners, Start-ups, MSMEs, OEMs, System Integrators, and End Users for participation as Development-cum-Production Partners (DcPPs) in the proposed project entitled “Establishment of Additive Packaging Center (A-PACK Center) at C-MET, Pune (Phase-2 Technology Development)”.

2. Tentative Calendar of Events

Sr. No.	Milestone	Date and time
1	Release of Expression of Interest (EOI)	09/09/2026
2	Last date for submission of queries via email	15/09/2026, 17: 30
3	Response to the queries	17/09/2026, 17:30
4	Last date for the submission of the EOI response	01/10/2026, 17:30

3. Background

The Department of Instrumentation and Applied Physics at the Indian Institute of Science (IISc), Bengaluru, is developing advanced additive manufacturing technologies for the fabrication of micro scale structures with applications in photonics, optics, semiconductor technologies, microfluidics, MEMS, biomedical devices, and advanced functional materials. As part of this initiative, IAP has developed technology for a **microns-resolution 3D printing platform** capable of fabricating complex three-dimensional microstructures and functional devices. The platform is intended to bridge the gap between conventional additive manufacturing and high-resolution fabrication.

IISc now invites **Expression of Interest (EOI) from capable Indian companies, technology companies, system integrators, equipment manufacturers, MSMEs and start-ups** interested in **co-developing, engineering, manufacturing and commercializing the next generation of submicron 3D printing systems**. Indian Institute of Science, Bengaluru, invites interested organizations to submit their Expression of Interest for participation in the proposed co-development programme.

Organizations with demonstrated capabilities in **precision engineering, additive manufacturing, optical systems, semiconductor equipment, mechatronics, automation, photonics and advanced manufacturing** are encouraged to participate.

The EoI is intended to identify suitable technology and industrial partners for subsequent detailed technical discussions and formulation of a mutually agreed co-development and commercialization framework which can be submitted to GOI for further evaluation.

The interested persons can directly send a copy with their details at:

Tapajyoti Das Gupta

Assistant professor

Laboratory of Advanced Nanostructures for Photonics and Electronics (LANSPE)

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4. Objective of the EoI

The objective of this EoI is to identify an industrial partner with the technical and manufacturing capability to work jointly:

1. Engineering and industrialization of the micron resolution 3D printing technology.
2. Development of a robust and user-friendly commercial system.
3. Integration of optical, mechanical, electronic and software subsystems.
4. Development of process-control and machine-control software.
5. Fabrication and assembly of engineering prototypes.
6. Performance validation and reliability testing.
7. Development of a manufacturable and scalable product architecture.
8. Establishment of a supply chain for critical components.
9. Joint demonstration and customer validation.
10. Commercialization and deployment of the technology in India and international markets.

The proposed collaboration is envisaged as a **technology co-development and commercialization partnership**, with the respective contributions, intellectual-property rights, commercialization rights and revenue-sharing arrangements to be mutually agreed upon between IISc and the selected partner.

5. Technology Platform

The proposed system is a **micron resolution 3D printer** based on advanced optical projection/additive-manufacturing principles.

The platform is intended to provide high-resolution fabrication of complex three-dimensional structures while retaining the advantages of additive manufacturing, including digital patterning, rapid design iteration and fabrication of geometrically complex structures.

Potential application areas include:

- Micro-optics and meta-optics
- Photonic structures
- Optical components
- Microfluidics
- MEMS and microsystems
- Biomedical microstructures
- Semiconductor and electronic components
- Microreactors
- Functional surfaces
- Research and development in advanced materials
- Micro/nanostructured devices

The technology is particularly relevant for applications requiring **micron feature sizes, three-dimensional geometries and rapid prototyping**.

6. Scope of Co-Development

The selected industrial partner is expected to work on one or more of the following activities.

6.1. System Engineering

The partner will support the conversion of the existing technology platform into an engineered product through:

- System architecture development
- Mechanical design
- Optical integration
- Electronics architecture
- Motion-control systems
- Environmental enclosure
- Thermal management
- Safety systems

- User-interface development

6.2 Optical System Development

The optical subsystem may include:

- UV/visible light source
- Projection optics
- High-resolution optical components
- Beam conditioning
- Optical alignment
- Optical monitoring
- Resolution optimization

The partner should have demonstrated capability in precision optical integration and alignment.

6.3 Precision Motion System

The system will require high-precision motion and positioning for controlled layer-by-layer fabrication.

Potential areas include:

- Precision stages
- Z-axis positioning
- Multi-axis positioning
- Closed-loop control
- Vibration management
- Calibration and compensation

6.4 Resin and Process Integration

The partner may work with IISc on integration of:

- UV-curable materials
- Photopolymer resins
- Material delivery systems
- Resin handling
- Exposure control
- Layer formation
- Process monitoring

6.5 Electronics and Control

The industrial partner will support development of:

- Machine-control electronics
- Motion controllers
- Exposure controllers
- Sensors
- Embedded systems
- Data acquisition
- Safety interlocks
- Communication interfaces

6.6 Software

The commercial system should include appropriate software for:

- 3D model preparation
- Slicing
- Support generation
- Exposure-pattern generation
- Process parameter control
- Machine operation
- Calibration
- Monitoring
- Data logging

Where appropriate, the platform should support integration with standard CAD and digital-manufacturing workflows.

7. Target Performance

The co-developed system is expected to target **micron fabrication capability**, with the final specifications to be established jointly during the engineering and validation phase.

The desired development targets may include:

Parameter	Target
Printing technology	High-resolution optical additive manufacturing
Feature size	micron
Fabrication	Three-dimensional structures
Digital fabrication	CAD-to-print workflow

Resolution	Target $\leq 1\ 0\mu\text{m}$, with further improvement based on IISc technology
Material	UV/photocurable materials
Process	Layer-by-layer / projection-based fabrication
Application	Micro-optics, photonics, MEMS, microfluidics and advanced manufacturing
Product development	Research prototype → engineering prototype → commercial system

The precise specifications, acceptance criteria and performance milestones will be finalized during the co-development agreement.

8. Role of IISc

IISc may provide:

- Core technology and scientific know-how
- Existing prototype/platform technology
- Optical and process-development expertise
- Fabrication and process knowledge
- Materials and process-development support
- Performance evaluation
- Technology validation
- Application development
- Access to research infrastructure
- Training and technical knowledge transfer
- Support for technology demonstration
- Joint development of new applications
- Release of funds to the concerned party as sanctioned by MeitY

IISc will work with the selected partner to facilitate technology translation from laboratory-scale demonstration to an engineered and commercially viable system.

9. Expected Role of the Industry Partner

The industry partner is expected to contribute expertise and resources in:

- Product engineering
- Mechanical design
- Precision manufacturing
- Optical integration

- Electronics
- Embedded systems
- Software
- Machine control
- Industrial design
- Component sourcing
- System assembly
- Testing and validation
- Quality assurance
- Regulatory compliance
- Manufacturing scale-up
- Field support
- Sales and marketing
- Commercialization

The partner should have the capability to take the system from an **engineering prototype to a manufacturable product**.

10. Co-Development Model

The proposed collaboration may follow a phased development model:

Phase I – Technology Assessment

- Technical due diligence
- System architecture
- Identification of engineering gaps
- Definition of performance specifications

Phase II – Engineering Development

- Mechanical and optical engineering
- Electronics development
- Software development
- Process integration
- Prototype engineering

Phase III – Engineering Prototype

- Fabrication of prototype system
- System integration
- Initial performance testing
- Resolution and repeatability assessment

Phase IV – Product Validation

- Reliability testing
- Application demonstrations
- User trials
- Process optimization
- Manufacturing documentation

Phase V – Commercialization

- Product finalization
- Manufacturing scale-up
- Supply-chain development
- Market deployment
- Customer support
- Training and service network

11. Intellectual Property

The existing intellectual property, technology, know-how, designs and background IP of IISc shall remain with the respective owners.

Any new intellectual property generated jointly during the co-development programme shall be governed by a mutually agreed **Technology Transfer / Co-Development Agreement**.

The agreement may address:

- Background IP
- Foreground IP
- Joint patents
- Licensing
- Manufacturing rights
- Commercialization rights
- Territory
- Exclusivity, if applicable
- Revenue sharing

- Technology transfer
- Confidentiality

The detailed IP framework will be finalized with the selected partner.

12. Commercialization Opportunity

The proposed technology has potential applications in several emerging markets where conventional 3D printing does not provide the required resolution.

Potential customers include:

- Semiconductor companies
- Photonics companies
- Optical-component manufacturers
- MEMS companies
- Biomedical-device companies
- Microfluidics companies
- Universities and research laboratories
- R&D centres
- Defence and aerospace organizations
- Start-ups
- Advanced manufacturing companies

The industry partner will be expected to contribute to market validation, customer identification, product positioning and commercialization strategy.

13. Preferred Industry Partner Profile

The EoI is open to companies having one or more of the following capabilities:

- Precision engineering
- Additive manufacturing
- 3D printing
- Optical systems
- Semiconductor equipment
- Nanotechnology
- Microfabrication
- Mechatronics
- Robotics

- Industrial automation
- Machine-tool development
- Photonics
- Advanced manufacturing

Preference may be given to organizations having demonstrated experience in **designing and manufacturing sophisticated capital equipment and taking laboratory technologies to commercial products.**

Start-ups and MSMEs with strong technological capability are also encouraged to participate.

14. Industry Contribution

Interested organizations are requested to indicate their proposed contribution in terms of:

1. Engineering manpower
2. Financial contribution
3. Manufacturing infrastructure
4. Component sourcing
5. Product development
6. Software development
7. Testing facilities
8. Commercialization capability
9. Market access
10. After-sales service and support

The contribution may be in cash, kind, engineering resources, manufacturing infrastructure or a combination thereof.

15. EoI Response

Interested organizations are requested to submit an Expression of Interest containing the following information:

A. Organization Profile

- Name and address
- Legal status
- Year of establishment
- Ownership structure
- Relevant business activities

B. Technical Capability

- Relevant technology expertise
- Existing manufacturing facilities
- Engineering capabilities
- Relevant products developed
- Experience in optical/mechatronic systems

C. Relevant Experience

- Previous technology-development projects
- Additive manufacturing experience
- Semiconductor/precision-equipment experience
- Product commercialization experience

D. Proposed Contribution

- Technical contribution
- Financial contribution
- Manufacturing contribution
- Human resources
- Commercialization support

E. Commercialization Plan

- Proposed target markets
- Potential customer segments
- Manufacturing strategy
- Expected product price range
- Sales and service strategy

F. Proposed Partnership Model

The organization may propose one or more models, including:

- Joint development
- Technology licensing
- Co-development and manufacturing
- Joint commercialization
- Strategic technology partnership
- Revenue-sharing model

16. Selection Criteria

Responses may be evaluated based on:

Criterion	Indicative Importance
Technical capability	High
Precision manufacturing capability	High
Optical/mechatronic integration	High
Product engineering capability	High
Financial commitment	Medium–High
Manufacturing infrastructure	High
Commercialization capability	High
Market access	Medium–High
Relevant experience	High
Long-term commitment	High

IISc may invite shortlisted organizations for technical discussions, demonstrations, site visits and detailed co-development negotiations.

17. Expected Outcome

The ultimate objective of the collaboration is to establish an **indigenously developed, commercially deployable micron 3D printing platform** with the capability to serve India's emerging requirements in semiconductor, photonics, microfabrication and advanced manufacturing.

The partnership is expected to create a pathway:

IISc Technology → Industrial Engineering → Prototype → Product Validation → Manufacturing → Commercialization

and thereby contribute to the development of **indigenous high-resolution additive-manufacturing equipment and advanced manufacturing capability in India.**

18. Eligibility criteria

18.1. General Eligibility Criteria Interested Industry Partners shall:

- a) Be incorporated/registered in India under the Companies Act, LLP Act, Partnership Act, MSME Act, or other applicable statutes.
- b) Possess valid PAN, GST, and statutory registrations.
- c) Not be blacklisted, debarred, or banned by any Central Government, State Government, PSU, Autonomous Body, or Research Organization.

- d) Have sound financial standing and operational capability.
- e) Demonstrate willingness to participate in technology development, manufacturing, testing, validation, commercialization, or deployment activities.

18.2. Technical Qualification –

Criteria for Interested Industry Partners Interested Industry Partners should possess expertise in one or more of the following areas:

- a) Advanced materials development (ceramics, LTCC, glass-ceramics, photopolymers, conductive materials, and thermal management materials).
- b) Additive manufacturing systems, Vat Polymerization, DLP-based printing technologies, automation, robotics, process monitoring, or machine development.
- c) Photonics packaging, optoelectronics packaging, semiconductor packaging, precision assembly, alignment, testing, and reliability evaluation.
- d) Optical design, simulation, AI-enabled design tools, CAD/CAM, DfAM, ADK development, or Multiphysics modeling.
- e) Pilot manufacturing, process engineering, product development, qualification, certification, and commercialization.
- f) End-user industries related to photonics, telecom, defense, aerospace, medical, sensing, semiconductor manufacturing, or advanced electronics. Preference may be given to organizations possessing prior experience in photonics, additive manufacturing, electronics packaging, LTCC technologies, or related domains.

18.3. Disclaimer: This EOI is intended solely for information gathering and identification of potential Developmentcum-Production Partners (DcPPs). Issuance of this EOI does not constitute a commitment by IISc to award any contract, funding support, partnership agreement, technology transfer arrangement, or procurement order. IISc reserves the right to accept, reject, modify, suspend, or cancel the EOI process at any stage without assigning any reason.

19. TERMS AND CONDITIONS

19.1. General Terms :

- Participation in this EOI is voluntary.
- Submission of EOI does not guarantee selection.
- IISc may seek additional information at any stage.
- All information provided shall be treated in accordance with applicable confidentiality requirements.
- Selected partners may be required to execute Non-Disclosure Agreements (NDAs) and other legal documents.
 - If the proposal is approved , funds from IISc will be transferred to the selected partner as per Sanction order.

19.2. Submission Requirements Interested Industry Partners shall submit:

- Company profile.
 - Completed Annexures
- Technical capability details.
- Financial information.
- Compliance statement.
- Non-blacklisting affidavit.
- Supporting technical and commercial documents.

Disqualification Criteria An EOI may be rejected if:

- Required information is incomplete.
- False or misleading information is provided.
- Eligibility criteria are not satisfied.
- Required declarations are not furnished.
- The organization is blacklisted, insolvent, or under legal restrictions.
- Submission is received after the prescribed deadline.

20. SUBMISSION DETAILS

20.1. How to Submit: Interested Industry Partners may submit their EOI along with the detailed information requested in previous sections, with supporting documentary proofs to the address given below.

Physical Submission: EoI responses should be submitted in a sealed envelope clearly marked with:

Expression of Interest for the identification of Development cum Production industry (DcPP) partners for the joint submission of a project towards the development of Establishment of Additive Packaging Center (A-PACK Center) at C-MET, Pune (Phase-2 Technology Development) with IISc collaborating on light engine development.

Company Name and Contact Details

Email Submission: Soft copy may also be submitted via email to the address mentioned below with the subject line: "Expression of Interest for the identification of Development cum Production industry (DcPP) partners for the joint submission of a project towards the Establishment of Additive Packaging Center (A-PACK Center) at C-MET, Pune (Phase-2 Technology Development) (IISc collaborating on light engine development)."

Submission Address Physical Submission: Instrumentation and applied physics, Indian Institute of Science Rama Road ,Bengaluru 560012,India,Phone- +91-80-2293-2349, Email: tapajyoti@iisc.ac.in

CONTACT INFORMATION: For any clarifications or queries regarding this EoI, please contact: Project Coordinator – For technical queries Dr. Tapajyoti Das Gupta), Instrumentation and applied physics, IISc, Bengaluru , India 560012 Email: tapajyoti@iisc.ac.in Phone: +91-80-2293-2349

ANNEXURES

Annexure-I (A): Basic Company Details

Annexure I (B): Interested Industry Partner Information Proforma

Annexure-II: Compliance Statement Template

Annexure-III: Technical Capability

Declaration **Annexure-IV:** Financial Details

Format

Annexure-V: Non-Blacklisting Affidavit Format

EoI - Annexure-I (A): Details to be furnished with EoI

1	Name of the Company	
	Type of the Company PSU/Public Ltd/Private Ltd/Registered Partnership firm/Others (specify)	
	Certificate of Registration /Incorporation No.(<i>Attach a copy of the Certificate</i>)	
	Address of the Registered Office	
	Name & Designation of Contact Person	
	Address with telephone No. & Email ID of Contact Person	
	Website address	
	Products/Services handled by the Company	
	No. of years of experience in the related area justified by orders executed	
	The last three years (<i>Attach copy of the audited statements</i>)	2023-2024 2024-2025 2025-2026
	Details of Income Tax Registration, GST registration, and other applicable registrations	
	PAN number	
	Available Manpower	Managerial: Engineers/Scientists: Technically skilled: Semi-Skilled: Un –skilled:
	Testing and Calibration Facility (Infrastructure and Equipment)	
	ISO certification/ In-house QA if any	
	Any other information, The Organization wishes to provide	
Declaration		
I/We hereby declare that the information given in the EoI and documents attached herewith are true & correct to the best of my/our knowledge and belief. I/We agree that in case any particulars are found incorrect at any time, C-MET has the right to cancel our EOI submission and/or any subsequent selection as development-cum-Production Partner (DcPP) for the proposed project towards the Development of Advanced Photonics Packaging Technologies using Additive Manufacturing, and all the payments, if any, to C-MET shall stand forfeited.		
Date :		
Place:		
Authorized Signatory (with official seal)		

Annexure-I (B): Interested Industry Partners Information Proforma

A. Organization Details

1. Legal Name of Organization: _____
2. Trade Name (if different): _____
3. Type of Organization: ☐ Proprietorship ☐ Partnership ☐ Private Ltd ☐ Public Ltd ☐ LLP ☐ Others (specify) _____
4. Year of Establishment: _____
5. Country of Registration: _____
6. Registration Number: _____
7. PAN Number: _____
8. GST Number: _____
9. TAN Number: _____

B. Contact Information

1. Registered Office Address: _____
2. Corporate Office Address: _____
3. PIN Code: _____
4. Telephone: _____
5. Email (Official): _____
6. Website: _____

C. Authorized Signatory Details

1. Name: _____
2. Designation: _____
3. Contact Number: _____
4. Email: _____
5. Authorization Letter Attached: ☐ Yes ☐ No

D. Key Personnel for This Project

1. Project Manager Name: _____
2. Technical Lead Name: _____
3. Contact Details: _____

E. Banking Details

1. Bank Name: _____
2. Branch Address: _____

3. Account Number: _____

4. IFSC Code: _____

5. Account Type: ☐ Current ☐ Savings

Annexure-II: Compliance Statement Template

COMPLIANCE STATEMENT

To, [Name of Organization] [Address]

Subject: Compliance Statement for EOI No. _____

Dear Sir/Madam,

We, [Vendor Name], having our registered office at [Address], hereby declare and confirm our compliance with the eligibility criteria and requirements specified in the Expression of Interest (EOI) document for [Project Name].

Technical Compliance:

S. No.	EOI Requirement	Compliance Status	Remarks
1.		☐ Yes ☐ No ☐ Partially	
2.		☐ Yes ☐ No ☐ Partially	
3.		☐ Yes ☐ No ☐ Partially	
4.		☐ Yes ☐ No ☐ Partially	
5.		☐ Yes ☐ No ☐ Partially	

Regulatory Compliance:

S. No.	Compliance Requirement	Status	Document Reference
1.	Valid Business Registration	☐ Yes ☐ No	
2.	GST Registration	☐ Yes ☐ No	
3.	PAN Card	☐ Yes ☐ No	
4.	ISO Certification (if applicable)	☐ Yes ☐ No	
5.	Industry-specific licenses	☐ Yes ☐ No	

Commercial Compliance:

- We accept the terms and conditions of the EOI: ☐ Yes ☐ No
- We have no conflict of interest: ☐ Confirmed
- We are not blacklisted by any government/PSU: ☐ Confirmed

Deviations (if any):

We understand that any false declaration may lead to disqualification and legal action.

For [Interested Industry Partners Name]

Signature: _____ Name: _____
Designation: _____ Company Seal: Date: _____
_____ Place: _____

Annexure-III: Technical Capability Declaration

TECHNICAL CAPABILITY DECLARATION

A. Organizational Capabilities

- 1. Technical Expertise:
 - Total Technical Staff: _____
 - PhDs: _____ | M.Tech/M.Sc: _____ | B.Tech/B.Sc: _____
 - Years of experience in relevant field: _____
- 2. Infrastructure:
 - Laboratory Facilities: ☐ Yes ☐ No
 - Testing Equipment: (List) _____
 - Quality Control Setup: ☐ Yes ☐ No
 - Certification: _____
- 3. Technology Partnerships:
 - List of collaborations with research institutions: _____
 - Technology licenses held: _____

B. Past Project Experience

S. No.	Project Name	Client	Duration	Project Value	Relevance to Current EOI
1.					
2.					
3.					

C. Key Technical Personnel

Name	Qualification	Specialization	Years of Experience	Role in Proposed Project

D. Research & Development Capabilities

- Annual R&D Budget: _____
- Number of Patents/Copyrights Filed/Granted: _____
- Ongoing Research Projects: _____

E. Quality Assurance

- Quality Management System: _____

• _____

F. Project Execution Methodology Brief description of approach to scientific projects (max 500 words):

G. Supporting Documents Attached: ☐ Company Profile ☐ Technical Team CVs ☐ Laboratory/Facility Photographs ☐ Equipment List with Specifications ☐ Quality Certificates ☐ Client Testimonials/Work Orders ☐ Publications/Patents (if applicable)

Declaration: I/We hereby declare that all information provided above is true and accurate to the best of my knowledge. I/We understand that any false information may result in disqualification.

For [Interested Industry Partners Name]

Signature: _____Name: _____

Designation: _____Company Seal: Date:_____

Annexure-IV: Financial Details Format

FINANCIAL DETAILS FORMAT

A. Annual Turnover Details

Financial Year	Annual Turnover (INR)	Turnover from Similar Projects	Audited/Provisional
2025-26			
2024-25			
2023-24			

B. Profit & Loss Summary

Particulars	FY 2023-24	FY 2024-25	FY 2025-26
Total Revenue			

C. Balance Sheet Summary

Particulars	As on 31.03.2024	As on 31.03.2025	As on 31.03.2026
Total Assets			
Current Assets			
Total Liabilities			
Current Liabilities			

E. Banking Arrangements

1. Banker's Name: _____
2. Branch: _____
3. Type of Facilities Availed: _____
4. Credit Limit Sanctioned: _____
5. Outstanding Amount: _____

G. Tax Compliance

- Income Tax Return filed for last 3 years: ☐ Yes ☐ No
- Any tax demands pending: ☐ Yes ☐ No (If yes, provide details: _____)

- GST Returns filed regularly: ☐ Yes ☐ No

H. Financial Capacity for This Project

- Estimated Project Value: _____
- Available Working Capital: _____
- Proposed Financial Arrangement: _____

I. Documents Attached: ☐ Audited Financial Statements (last 3 years) ☐ Income Tax Returns (last 3 years) ☐ GST Returns (last 6 months) ☐ Bank Solvency Certificate ☐ CA Certificate for turnover
☐ Credit Rating Certificate (if applicable)

Declaration: I/ We hereby certify that the financial information provided above is true and correct as per our books of accounts and audited financial statements.

For [Interested Industry Partners Name]

Signature: _____ Name: _____

Designation: _____ Company Seal: Date: _____

Annexure-V: Non-Blacklisting

Affidavit Format NON-BLACKLISTING AFFIDAVIT

AFFIDAVIT

I, _____ (Name), son/daughter/wife of _____,
aged

_____ years, residing at _____, being the
Authorized Signatory of M/s _____ (Name of the Company), having its
registered office at

_____, do hereby solemnly affirm and declare as
under:

1. That I am the authorized signatory of the above-named company and am competent to swear this affidavit on behalf of the company.
 2. That our company/firm M/s _____ has submitted an Expression of Interest (EOI) in response to EOI No. ____ dated _____ for [Project Name].
 3. That our company/firm has not been blacklisted, debarred, or banned by any Central Government/State Government/Public Sector Undertaking/Autonomous Body/Research Institution in India or abroad as on the date of submission of this EOI.
 4. That no criminal proceedings are pending against our company/firm or its directors/partners/proprietors in any court of law.
 5. **That our company/firm has not been declared insolvent or bankrupt, and no insolvency proceedings are pending against us.**
 6. **That our company/firm has not been involved in any fraudulent, corrupt, or unethical business practices.**
 7. That no investigation by any regulatory or investigative agency is currently ongoing against our company/firm or its promoters/directors.
 8. That we have never been terminated from any contract due to non-performance or misrepresentation.
 9. That we undertake to immediately inform C-MET if any of the above declarations become incorrect during the EoI evaluation process.
- Disqualify our EOI without any prior notice
 - Terminate any contract awarded to us
 - Forfeit any performance security/earnest money deposit
 - Debar us from future opportunities
 - Take any legal action deemed appropriate

10. That all information provided in this affidavit is true and correct to the best of my knowledge and belief.

NOTARY PUBLIC

Sworn before me on this ____ day of _____ 20__ at _____.

Signature: _____ Name: _____

Notary Registration No.: _____
Seal: _____

Note: This affidavit should be executed on non-judicial stamp paper of appropriate value as per state regulations (typically Rs. 100-500) and duly notarized.